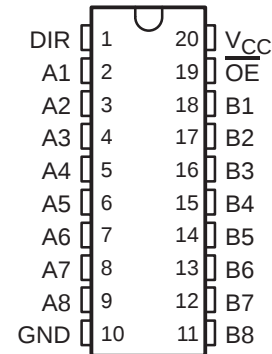


- **EPIC™** (Enhanced-Performance Implanted CMOS) Submicron Process
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model ($C = 200$ pF, $R = 0$)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages

DB, DW, OR PW PACKAGE
(TOP VIEW)



description

This octal bus transceiver is designed for 2.7-V to 3.6-V V_{CC} operation.

The SN74LVCR2245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so the buses are effectively isolated.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVCR2245 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation



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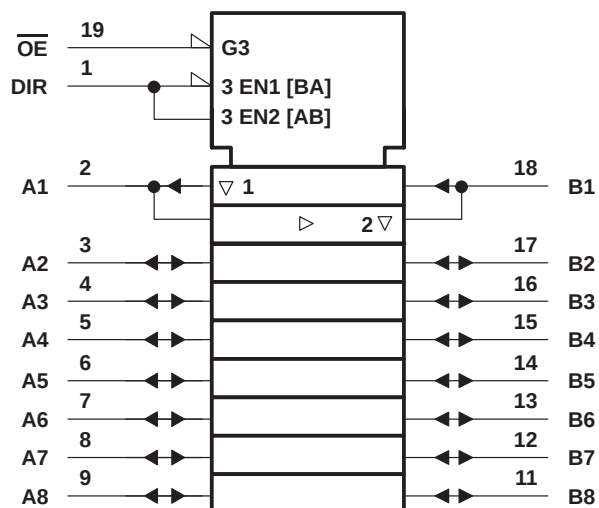
SN74LVCR2245

OCTAL BUS TRANSCEIVER

WITH 3-STATE OUTPUTS

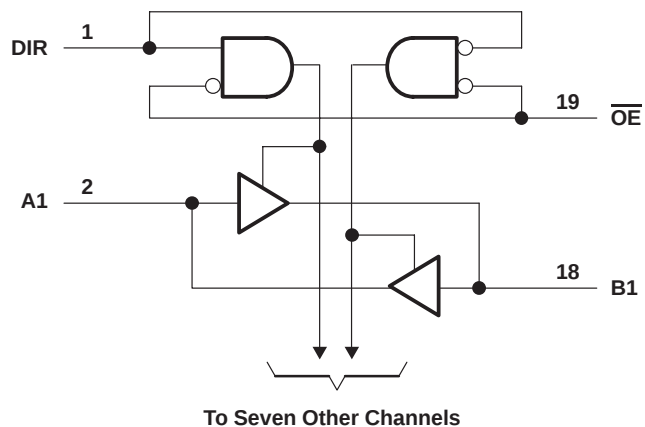
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 6.5 V
Input voltage range, V_I (see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high-impedance state, V_O (see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, V_O (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) (see Note 2)	±50 mA
Continuous current through V_{CC} or GND	±100 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 3): DB package	0.6 W
DW package	1.6 W
PW package	0.7 W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The value of V_{CC} is provided in the recommended operating conditions table.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage	Operating	2	3.6	V
		Data retention only	1.5		
V_{IH}	High-level input voltage	$V_{CC} = 2.7$ V to 3.6 V	2		V
V_{IL}	Low-level input voltage	$V_{CC} = 2.7$ V to 3.6 V		0.8	V
V_I	Input voltage		0	5.5	V
V_O	Output voltage	High or low state	0	V_{CC}	V
		3 state	0	5.5	
I_{OH}	High-level output current	$V_{CC} = 2.7$ V		–8	mA
		$V_{CC} = 3$ V		–12	
I_{OL}	Low-level output current	$V_{CC} = 2.7$ V		8	mA
		$V_{CC} = 3$ V		12	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	10	ns/V
T_A	Operating free-air temperature		–40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

SN74LVCR2245

OCTAL BUS TRANSCEIVER

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			V _{CC}	MIN	TYP [†]	MAX	UNIT
V _{OH}		I _{OH} = −100 μA	2.7 V to 3.6 V	V _{CC} −0.2			V
		I _{OH} = −4 mA	2.7 V	2.2			
		I _{OH} = −6 mA	3 V	2.4			
		I _{OH} = −8 mA	2.7 V	2			
		I _{OH} = −12 mA	3 V	2			
V _{OL}		I _{OL} = 100 μA	2.7 V to 3.6 V			0.2	V
		I _{OL} = 4 mA	2.7 V			0.4	
		I _{OL} = 6 mA	3 V			0.55	
		I _{OL} = 8 mA	2.7 V			0.6	
		I _{OL} = 12 mA	3 V			0.8	
I _I		V _I = 5.5 V or GND	3.6 V			±5	μA
I _{OZ} [‡]		V _O = V _{CC} or GND	3.6 V			±10	μA
		V _O = 3.6 V or 5.5 V	2.7 V to 3.6 V			±50	
I _{CC}		V _I = V _{CC} or GND, I _O = 0	3.6 V			10	μA
ΔI _{CC}		One input at V _{CC} − 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V			500	μA
C _i	Control inputs	V _I = V _{CC} or GND	3.3 V			3.3	pF
C _O	A or B ports	V _O = V _{CC} or GND	3.3 V			5.4	pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

[‡] For I/O ports, the parameter I_{OZ} includes the input leakage current.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd}	A or B	B or A	1.5	7.5	8.5		ns
t _{en}	$\overline{\text{OE}}$	A or B	1.5	9.5	10.5		ns
t _{dis}	$\overline{\text{OE}}$	A or B	1.5	7.5	8.5		ns
t _{sk(o)} [§]			1				ns

[§] Skew between any two outputs of the same package switching in the same direction. This parameter is warranted but not production tested.

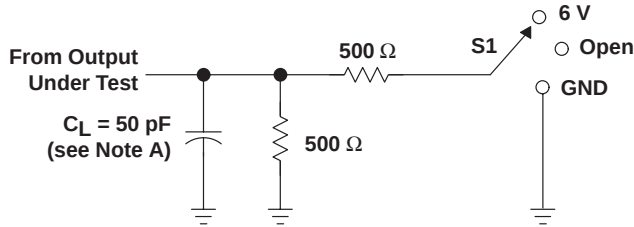
operating characteristics, V_{CC} = 3.3 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C _{pd}	Power dissipation capacitance per transceiver	C _L = 50 pF, f = 10 MHz		33	pF
				2	

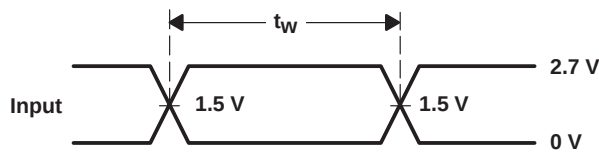


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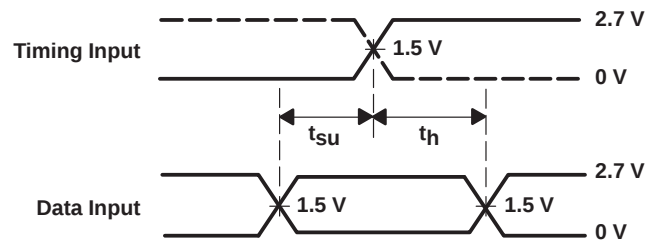
PARAMETER MEASUREMENT INFORMATION



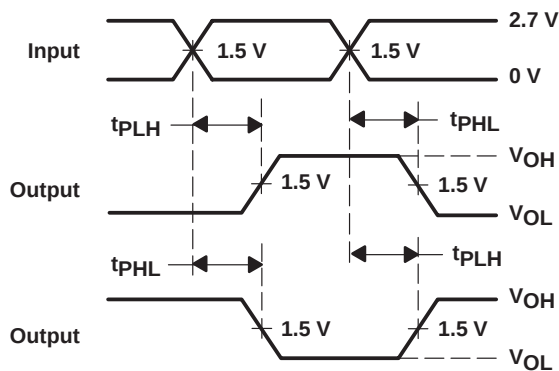
LOAD CIRCUIT



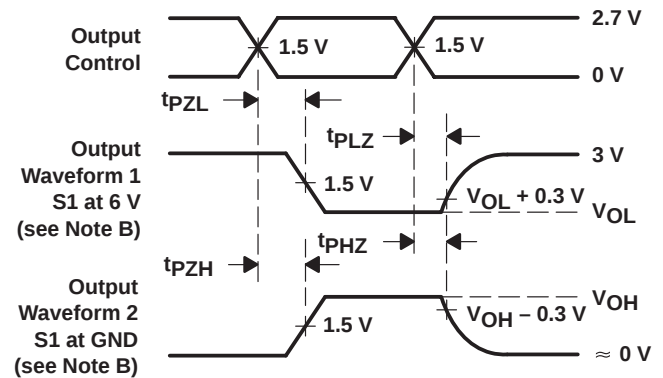
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PZL} and t_{PZH} are the same as t_{en} .
 - F. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

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